

ON Semiconductor			10/15/2019	
Base Part		FDC658P	HF	Pb-free
Orderable Part		FDC658P	Total weight (mg)	17.164
Homogenous Material	Weight (mg)	Substance in Mat.	CAS #	% Avg. Weight
Die	0.172	Silicon (Si)	7440-21-3	100
Lead Frame	8.254	Silver (Ag)	7440-22-4	0.26653744
		Zinc (Zn)	7440-66-6	0.12115338
		Iron (Fe)	7439-89-6	2.39883693
		Copper (Cu)	7440-50-8	97.18924158
		Phosphorus (P)	7723-14-0	0.02423068
Mold Compound-Black	7.596	Ortho Cresol Novolac Resin	29690-82-2	20.01053186
		Carbon Black (C)	1333-86-4	1.00052659
		Fused Silica (SiO2)	60676-86-0	78.98894155
Plating	1.13	Tin (Sn)	7440-31-5	100
Wire Bond - Cu	0.012	Copper (Cu)	7440-50-8	100
<p>Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the most accurate information, we cannot guarantee to its accuracy since the data has been compiled based on the ranges provided, and some information provided by the subcontractors and raw material suppliers may have been withheld to protect their business proprietary information. Thus this information is provided only as estimates, and do not include trace levels fo dopants and metal materials contained within silicon devices in the finished products. There is no intentional use of Mercury, Hexavalent Chromium, Cadmium, PBB or PBDE (5 of the 6 RoHS banned substances) in this or any of our other products. For further explanation on material composition calculations, please view our Product Chemical Content Brochure at:</p> <p>http://www.onsemi.com/pub/Collateral/BRD8022-D.PDF</p>				